

# MN3673RE

Color CCD Linear Image Sensor  
with 2592 Bits each for R, G, and B Colors

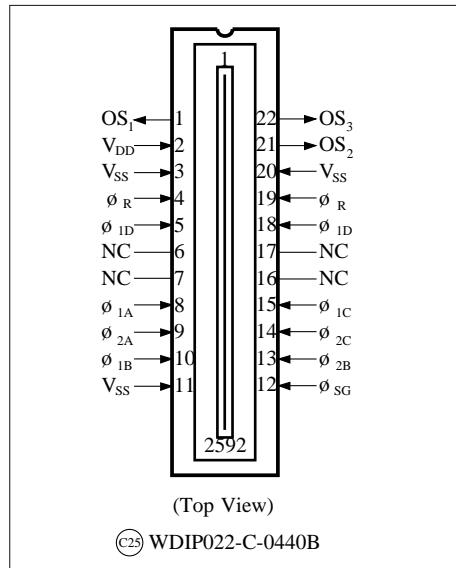
## ■ Overview

The MN3673RE is a 2592-pixel high sensitivity CCD linear image sensor combining photo-sites using low dark output floating photodiodes and CCD analog shift registers for read out. It provides large output at a high S/N ratio for visible light inputs over a wide range of wavelength.

## ■ Features

- 7776 (2592  $\times$  R, G, B) floating photodiodes and n-channel buried type CCD shift registers for read out are integrated in a single chip.
- Since the spacing between the photodiode lines of different colors is small, it is possible to greatly reduce the memory for compensation between lines. (1 line between R-B, 10 lines between B-G)
- The configuration of the signal processing circuits such as the preamplifier, sample and hold circuit, etc., becomes simpler since the separate signal output pins are provided for the pixels of each of the colors R, G, and B.
- RGB primary colors type on-chip color filters are used for color separation.
- The dark signal output voltage has been suppressed to a very low level due to the use of photodiodes with a new structure. (0.2mV (typ.) at an accumulation time of 10ms.)
- Operation with a single +12V positive power supply.

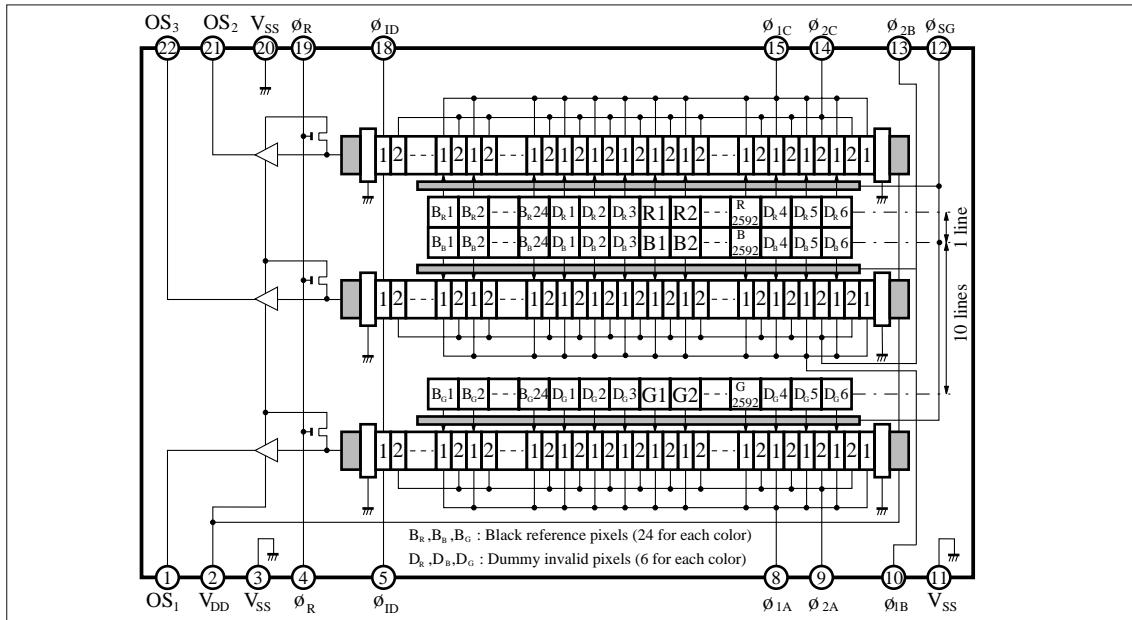
## ■ Pin Assignments



## ■ Application

- Color graphic read out in color copying machines, color scanners, and color fax machines.

## ■ Block Diagram



■ Absolute Maximum Ratings (Ta=25°C, Vss=0V)

Parameter	Symbol	Rating	Unit
Power supply voltage	V <sub>DD</sub>	-0.3 to +17	V
Input pin voltage	V <sub>I</sub>	-0.3 to +17	V
Output pin voltage	V <sub>O</sub>	-0.3 to +17	V
Operating temperature range	T <sub>opr</sub>	0 to + 60	°C
Storage temperature range	T <sub>stg</sub>	-25 to + 85	°C

■ Operating Conditions

- Voltage conditions (Ta=−20 to + 60°C, Vss=0V)

Parameter	Symbol	Condition	min	typ	max	Unit
Power supply voltage	V <sub>DD</sub>		11.4	12.0	13.0	V
CCD shift register clock High level	V <sub>φH</sub>	(φ <sub>1A</sub> ~ φ <sub>1D</sub> , φ <sub>2A</sub> ~ φ <sub>2C</sub> )	V <sub>DD</sub> -1	V <sub>DD</sub>	V <sub>DD</sub>	V
CCD shift register clock Low level	V <sub>φL</sub>	(φ <sub>1A</sub> ~ φ <sub>1D</sub> , φ <sub>2A</sub> ~ φ <sub>2C</sub> )	0	0.5	0.8	V
Shift gate clock High level	V <sub>SH</sub>	(φ <sub>SG</sub> )	V <sub>DD</sub> -1	V <sub>DD</sub>	V <sub>DD</sub>	V
Shift gate clock Low level	V <sub>SL</sub>	(φ <sub>SG</sub> )	0	0.5	0.8	V
Reset gate clock High level	V <sub>RH</sub>	(φ <sub>R</sub> )	V <sub>DD</sub> -1	V <sub>DD</sub>	V <sub>DD</sub>	V
Reset gate clock Low level	V <sub>RL</sub>	(φ <sub>R</sub> )	0	0.5	0.8	V

- Timing conditions (Ta=−20 to + 60°C)

Parameter	Symbol	Condition	min	typ	max	Unit
Shift register clock frequency	f <sub>C</sub>	f <sub>C</sub> =f <sub>R</sub> =1/2T	0.1	—	5	MHz
Reset clock frequency	f <sub>R</sub>		0.1	—	5	MHz
Shift register clock rise time	t <sub>Cr</sub>	See timing diagram	0	20	50	ns
Shift register clock fall time	t <sub>Cf</sub>		0	20	50	ns
Shift clock rise time	t <sub>Sr</sub>		0	15	50	ns
Shift clock fall time	t <sub>Sf</sub>		0	15	50	ns
Shift clock set up time	t <sub>Ss</sub>		250	400	1000	ns
Shift clock pulse width	t <sub>Sw</sub>		1.0	1.8	10	μs
Shift clock hold time	t <sub>Sh</sub>		0	—	1	μs
Reset clock rise time	t <sub>Rr</sub>		0	10	20	ns
Reset clock fall time	t <sub>Rf</sub>		0	10	20	ns
Reset clock set up time	t <sub>Rs</sub>		0.7T	—	—	ns
Reset clock pulse width	t <sub>Rw</sub>		20	30	—	ns
Reset clock hold time	t <sub>Rh</sub>		5	10	—	ns

■ Electrical Characteristics

- Clock input capacitance (Ta=0 to + 60°C)

Parameter	Symbol	Condition	min	typ	max	Unit
Shift register clock input capacitance	C <sub>1A</sub> , C <sub>1B</sub> C <sub>1C</sub> , C <sub>2A</sub> C <sub>2B</sub> , C <sub>2C</sub>	V <sub>IN</sub> =12V, f=1MHz	—	300	—	pF
Shift register final stage clock input capacitance	C <sub>ID</sub>		—	10	—	pF
Reset clock input capacitance	C <sub>RS</sub>		—	10	—	pF
Shift clock input capacitance	C <sub>SG</sub>		—	250	—	pF

- DC characteristics

Parameter	Symbol	Condition	min	typ	max	Unit
Power supply current	I <sub>DD</sub>	V <sub>DD</sub> =+12V	—	10	—	mA

### ■ Electrical Characteristics (continued)

- AC characteristics

Parameter	Symbol	Condition	min	typ	max	Unit
Signal output delay time	$t_{OS}$		—	50	—	ns

### ■ Optical Characteristics

<Inspection conditions>

- $T_a=25^\circ C$ ,  $V_{DD}=12V$ ,  $V_{SH}=V_{RH}=12V$  (pulse),  $f_C=f_R=1MHz$ ,  $T_{int}$  (accumulation time)=10ms
- Light source: Daylight type fluorescent lamp with IR/UV cutting filter
- Optical system: A slit with an aperture dimensions of 20mm  $\times$  20mm is used with a slit to sensor spacing of 200mm (equivalent to  $F=10$ ).
- Load resistance = 100k Ohms
- These specifications apply to the 2592 valid pixels for each color excluding the dummy pixels D1 to D6.

Parameter	Symbol	Condition	min	typ	max	Unit
Responsivity	$R_R$		0.7	1.0	1.3	V/lx·s
	$R_G$		1.4	2.0	2.6	
	$R_B$		1.0	1.4	1.8	
Photo response non-uniformity	PRNU	Note 1	—	7	15	%
Saturation output voltage	$V_{SAT}$	Note 2	0.9	1.2	—	V
Saturation exposure	$SE_R$	Note 2	0.69	1.20	—	lx·s
	$SE_G$	Note 2	0.35	0.60	—	
	$SE_B$	Note 2	0.50	0.86	—	
Dark signal output voltage	$V_{DRK}$	Dark condition, see Note 3	—	0.2	2.0	mV
Dark signal output non-uniformity	DSNU	Dark condition, see Note 3	—	0.1	1.0	mV
Shift register total transfer efficiency	STTE		92	—	—	%
Output impedance	$Z_O$		—	—	1	k $\Omega$
Dynamic range	DR	Note 4	—	6000	—	
Signal output pin DC level	$V_{OS}$	Absolute DC level of $OS_1$ , $OS_2$ , $OS_3$ , see Note 5	2.5	4.0	5.5	V
Signal output pin DC level difference	$\Delta V_{OS}$	Relative DC difference between $OS_1$ , $OS_2$ , $OS_3$ , see Note 5	—	50	200	mV

Note 1) The photo response non-uniformity (PRNU) is defined by the following equation, where  $X_{ave}$  is the average output voltage of the 2592 valid pixels and  $\Delta x$  is the absolute value of the difference between  $X_{ave}$  and the voltage of the maximum (or minimum) output pixel, when the surface of the photo-sites is illuminated with light having a uniform distribution over the entire surface.

$$PRNU = \frac{\Delta x}{X_{ave}} \times 100 (\%)$$

The incident light intensity shall be 50% of the standard saturation.

Note 2) The Saturation output voltage ( $V_{SAT}$ ) is defined as the output voltage at the point when the linearity of the photoelectric characteristics cannot be maintained as the incident light intensity is increased. (The light intensity of exposure at this point is called the saturation exposure.)

Note 3) The dark signal output voltage ( $V_{DRK}$ ) is defined as the average output voltage of the 2592 pixels in the dark condition at  $T_a=25^\circ C$  and  $T_{int}=10ms$ . Normally, the dark output voltage doubles for every 8 to 10°C rise in  $T_a$ , and is proportional to  $T_{int}$ .

The dark signal output non-uniformity (DSNU) is defined as the difference between the maximum output voltage among all the valid pixels and  $V_{DRK}$  in the dark condition at  $T_a=25^\circ C$  and  $T_{int}=10ms$ .

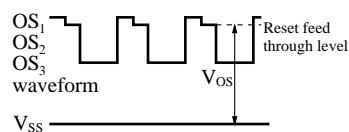


Note 4) The dynamic range is defined by the following equation.

$$DR = \frac{V_{SAT}}{V_{DRK}}$$

Since the dark signal voltage is proportional to the accumulation time, the dynamic range becomes wider when the accumulation time is shorter.

Note 5) The signal output pin DC level ( $V_{OS}$ ) and the compensation output pin DC level ( $V_{DS}$ ) are the voltage values shown in the following figure.



### ■ Pin Descriptions

Pin No.	Symbol	Pin name	Condition
1	OS <sub>1</sub>	Signal output 1 (Green)	
2	V <sub>DD</sub>	Power supply	
3	V <sub>SS</sub>	Ground	
4	φ <sub>R</sub>	Reset clock	Internally connected to pin 19.
5	φ <sub>1D</sub>	CCD final stage clock (Phase 1)	Internally connected to pin 18.
6	NC	Non connection	
7	NC	Non connection	
8	φ <sub>1A</sub>	CCD clock (Phase 1)	
9	φ <sub>2A</sub>	CCD clock (Phase 2)	
10	φ <sub>1B</sub>	CCD clock (Phase 1)	
11	V <sub>SS</sub>	Ground	
12	φ <sub>SG</sub>	Shift clock gate	
13	φ <sub>2B</sub>	CCD clock (Phase 2)	
14	φ <sub>2C</sub>	CCD clock (Phase 2)	
15	φ <sub>1C</sub>	CCD clock (Phase 1)	
16	NC	Non connection	
17	NC	Non connection	
18	φ <sub>1D</sub>	CCD final stage clock (Phase 1)	
19	φ <sub>R</sub>	Reset clock	
20	V <sub>SS</sub>	Ground	
21	OS <sub>2</sub>	Signal output 2 (Red)	
22	OS <sub>3</sub>	Signal output 3 (Blue)	

Note) Connect all NC pins externally to V<sub>SS</sub> (GND).

### ■ Construction of the Image Sensor

The MN3673RE can be made up of the three sections of—a) photo detector region, b) CCD transfer region (shift register), and c) output region.

#### a) Photo detector region

- The photoelectric conversion device consists of an 11 $\mu$ m floating photodiode and a 3 $\mu$ m channel stopper (isolation region) per pixel, and such 2592 pixels per color are arranged in a linear row with a pitch of 14 $\mu$ m along the main scanning direction with the pixel rows of different colors being placed parallel to each other.
- There is a spacing of one line between R-B in the sideways scanning direction (center to center spacing of 14 $\mu$ m) and a 10 line spacing between B-G in the sideways scanning direction (center to center spacing of 140 $\mu$ m).
- The photo detector's windows are 14 $\mu$ m  $\times$  14 $\mu$ m squares and light incident on areas other than these windows is optically shut out.
- The photo detector is provided with 24 optically shielded pixels (black reference pixels) which serve as the black reference.

#### b) CCD Transfer region (shift register)

- The light output that has been photoelectrically converted is transferred to the CCD transfer for each odd and even pixel at the timing of the shift clock (φ<sub>SG</sub>). The optical signal

charge transferred to this analog shift register is successively transferred out and guided to the output.

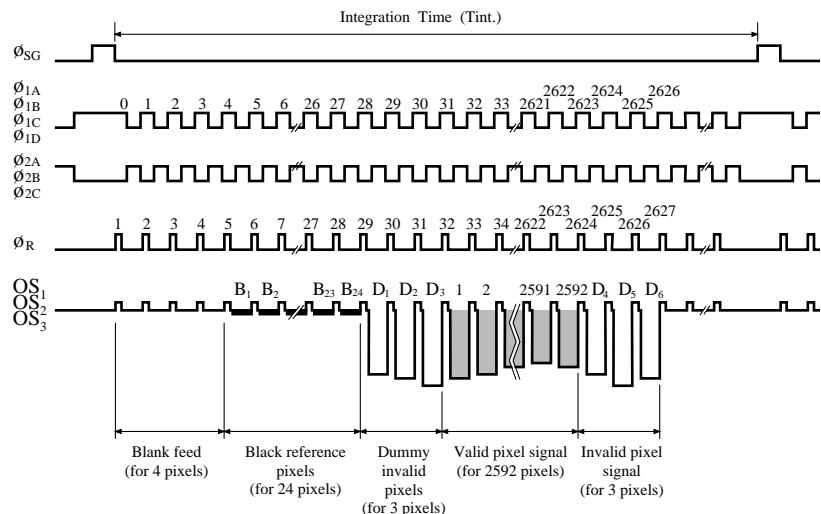
- A buried type CCD that can be driven by a two phase clock (φ<sub>1</sub>, φ<sub>2</sub>) is used for the analog shift register.
- The last gate of the CCD transfer region is connected to an independent pin (φ<sub>1D</sub>). By driving this pin independent of the other pins by a clock driver, it is possible to speed up the flow of signal charge into the charge to voltage conversion region thereby making the output waveform rise sharply. This makes it easy to obtain margin of the signal processing time during high speed drive operation.

#### c) Output region

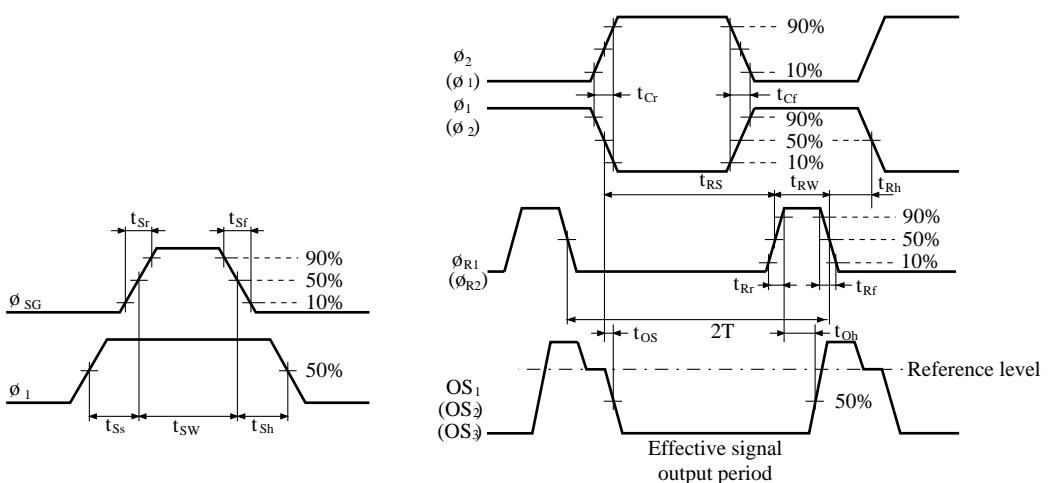
- The signal charge transferred to the output region is first sent to the charge to voltage conversion region where it is converted into a voltage level corresponding to the amount of the signal charge, and then output after impedance conversion in a two stage source follower amplifier.

■ Timing Diagram

(1) I/O timing



(2) Drive timing



■ Graphs and Characteristics

Spectral Response Characteristics

